

LEXANTM COPOLYMER EXL1414H

REGION ASIA

DESCRIPTION

Opaque PC-Siloxan copolymer with excellent processability. Medium flow, extreme low temperature ductile. Enhanced hydrolytic stability. Only available in black color.

TYPICAL PROPERTY VALUES

Revision 20190103

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	56	MPa	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	50	MPa	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	6	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	98	%	ASTM D 638
Tensile Modulus, 50 mm/min	2020	MPa	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	92	MPa	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	2230	MPa	ASTM D 790
Tensile Stress, yield, 50 mm/min	57	MPa	ISO 527
Tensile Stress, break, 50 mm/min	60	MPa	ISO 527
Tensile Strain, yield, 50 mm/min	6	%	ISO 527
Tensile Strain, break, 50 mm/min	120	%	ISO 527
Tensile Modulus, 1 mm/min	2150	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	85	MPa	ISO 178
Flexural Modulus, 2 mm/min	2250	MPa	ISO 178
IMPACT			
Izod Impact, notched, 23°C	865	J/m	ASTM D 256
Izod Impact, notched, -30°C	774	J/m	ASTM D 256
Instrumented Impact Total Energy, 23°C	70	J	ASTM D 3763
Instrumented Impact Total Energy, -30°C	77	J	ASTM D 3763
Izod Impact, unnotched 80*10*3 +23°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, unnotched 80*10*3 -30°C	NB	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*3 +23°C	70	kJ/m ²	ISO 180/1A
Izod Impact, notched 80*10*3 -30°C	60	kJ/m ²	ISO 180/1A
Charpy 23°C, V-notch Edgew 80*10*3 sp=62mm	70	kJ/m ²	ISO 179/1eA
Charpy -30°C, V-notch Edgew 80*10*3 sp=62mm	65	kJ/m ²	ISO 179/1eA
Charpy 23°C, Unnotch Edgew 80*10*3 sp=62mm	NB	kJ/m ²	ISO 179/1eU
Charpy -30°C, Unnotch Edgew 80*10*3 sp=62mm	NB	kJ/m ²	ISO 179/1eU
THERMAL			
Vicat Softening Temp, Rate B/50	145	°C	ASTM D 1525
HDT, 0.45 MPa, 3.2 mm, unannealed	139	°C	ASTM D 648
HDT, 1.82 MPa, 3.2mm, unannealed	124	°C	ASTM D 648
CTE, -40°C to 40°C, flow	7.E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	7.E-05	1/°C	ASTM E 831
CTE, 23°C to 80°C, flow	7.2E-05	1/°C	ISO 11359-2

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CTE, 23°C to 80°C, xflow	7.2E-05	1/°C	ISO 11359-2
Ball Pressure Test, 125°C +/- 2°C	PASSES	-	IEC 60695-10-2
Vicat Softening Temp, Rate B/50	145	°C	ISO 306
Vicat Softening Temp, Rate B/120	146	°C	ISO 306
HDT/Be, 0.45MPa Edgew 120*10*4 sp=100mm	140	°C	ISO 75/Be
HDT/Ae, 1.8 MPa Edgew 120*10*4 sp=100mm	128	°C	ISO 75/Ae
PHYSICAL			
Specific Gravity	1.18	-	ASTM D 792
Mold Shrinkage, flow, 3.2 mm	0.4 – 0.8	%	SABIC method
Melt Flow Rate, 300°C/1.2 kgf	10	g/10 min	ASTM D 1238
Density	1.19	g/cm ³	ISO 1183
Water Absorption, (23°C/sat)	0.35	%	ISO 62
Moisture Absorption (23°C / 50% RH)	0.15	%	ISO 62
Melt Volume Rate, MVR at 300°C/1.2 kg	9	cm ³ /10 min	ISO 1133
INJECTION MOLDING			
Drying Temperature	120	°C	
Drying Time	3 – 4	hrs	
Drying Time (Cumulative)	48	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	295 – 315	°C	
Nozzle Temperature	290 – 310	°C	
Front - Zone 3 Temperature	295 – 315	°C	
Middle - Zone 2 Temperature	280 – 305	°C	
Rear - Zone 1 Temperature	270 – 295	°C	
Mold Temperature	70 – 95	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	40 – 70	rpm	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.025 – 0.076	mm	

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